

Service Guide Specification

답 당	관 리 자
Park H.J 04.08.31	KIM J.O 04.08.31

1. Model Description

MODEL	L1930SQSNTM	BRAND	LG	Part No.	3828TSL085D
SUFFIX	SLEURW	Product Name	FLATRON L1930SQ		

2. Printing Specification

1. Trim Size (Format) : 215mm x 280 mm

2. Printing Colors

- Cover : LG COLORS
- Inside : Black

3. Stock (Paper)

- Cover : Snow White 150 g/m²
- Inside : Snow White 100 g/m²

4. Printing Method :

5. Bindery : Saddle stitch

6. Language : English

7. Number of pages : 28

3. Special Instructions

(1) Origin Notification

- | | |
|--------------------------------|-----------------------------|
| * LGEDI : Printed in Indonesia | * LGEWA : Printed in U.K. |
| * LGESP : Printed in Brazil | * LGEMX : Printed in Mexico |
| * LGENT : Printed in China | * LGEIL : Printed in India |

4. Changes

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1				
REV. NO.	MM/DD/YY	SIGNATURE	CHANGE NO.	CHANGE CONTENTS

Pagination sheet

P/NO.3828TSL085D
Total pages : 28pages

Cover	Front Cover inside 2	English 3	English 4	English 5	English	English
	English	English	English 24	English 25	English 26	Rear Cover Inside 27
						Rear Cover



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E-mail:<http://www.LGService.com/techsup.html>

COLOR MONITOR SERVICE MANUAL

CHASSIS NO. : CL-61

MODEL: FLATRON L1930SQ (L1930SQSNTM-AL**R)

() **Same model for Service

CAUTION

BEFORE SERVICING THE UNIT,
READ THE **SAFETY PRECAUTIONS** IN THIS MANUAL.



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SPECIFICATIONS

1. LCD CHARACTERISTICS

Type : TFT Color
 Size : 19 inch
 Pixel Pitch : 0.294 (H) x 0.294 (V)
 Color Depth : 16.2M colors
 Electrical Interface : LVDS
 Surface Treatment : Hard-coating(3H), Anti-Glare
 Operating Mode : Normally White, Transmissive mode
 Backlight Unit : Top/Bottom edge side 4-CCFL

2. OPTICAL CHARACTERISTICS

2-1. Viewing Angle by Contrast Ratio ≥ 10
 Left : -60° min., -70°(Typ) Right : +60° min., +70°(Typ)
 Top : +65° min., +75°(Typ) Bottom : -55° min., -65°(Typ)

2-2. Luminance : 200(min), 250(Typ)

2-3. Contrast Ratio : 300(min), 500(Typ)

3. SIGNAL (Refer to the Timing Chart)

3-1. Sync Signal
 • Type : Separate Sync,
 SOG (Sync On Green)
 Composite Sync

3-2. Video Input Signal
 1) Type : R, G, B Analog
 2) Voltage Level : 0~0.7 V
 3) Input Impedance : 75 Ω

3-3. Operating Frequency
 Horizontal : 30 ~ 83kHz
 Vertical : 56 ~ 75Hz

4. Max. Resolution

Analog : 1280 x 1024 / 75Hz

5. POWER SUPPLY

5-1. Power : AC 100~240V, 50/60Hz , 0.6A

5-2. Power Consumption

MODE	H/V SYNC	VIDEO	POWER CONSUMPTION	LED COLOR
POWER ON (NORMAL)	ON/ON	ACTIVE	less than 43 W	GREEN
STAND-BY	OFF/ON	OFF	less than 1 W	AMBER
SUSPEND	ON/OFF	OFF	less than 1 W	AMBER
DPMS OFF	OFF/OFF	OFF	less than 1 W	AMBER
POWER S/W Off	-	-	less than 1 W	Off

6. ENVIRONMENT

6-1. Operating Temperature: 10°C~35°C (50°F~95°F)
 (Ambient)

6-2. Relative Humidity : 10%~80%
 (Non-condensing)

6-3. MTBF : 50,000 Hours(Min)

7. DIMENSIONS (with TILT/SWIVEL)

Width : 444.4 mm (17.50")
 Depth : 108.7 mm (4.28")
 Height : 423.8 mm (16.68")

8. WEIGHT (with TILT/SWIVEL)

Net. Weight : 6.5 kg (14.33 lbs)
 Gross Weight : 8.8 kg (19.40 lbs)

PRECAUTION

WARNING FOR THE SAFETY-RELATED COMPONENT.

- There are some special components used in LCD monitor that are important for safety. **These parts are marked \triangle on the schematic diagram and the replacement parts list.** It is essential that these critical parts should be replaced with the manufacturer's specified parts to prevent electric shock, fire or other hazard.
- Do not modify original design without obtaining written permission from manufacturer or you will void the original parts and labor guarantee.

TAKE CARE DURING HANDLING THE LCD MODULE WITH BACKLIGHT UNIT.

- Must mount the module using mounting holes arranged in four corners.
- Do not press on the panel, edge of the frame strongly or electric shock as this will result in damage to the screen.
- Do not scratch or press on the panel with any sharp objects, such as pencil or pen as this may result in damage to the panel.
- Protect the module from the ESD as it may damage the electronic circuit (C-MOS).
- Make certain that treatment person's body are grounded through wrist band.
- Do not leave the module in high temperature and in areas of high humidity for a long time.
- The module not be exposed to the direct sunlight.
- Avoid contact with water as it may a short circuit within the module.
- If the surface of panel become dirty, please wipe it off with a softmaterial. (Cleaning with a dirty or rough cloth may damage the panel.)

\triangle CAUTION

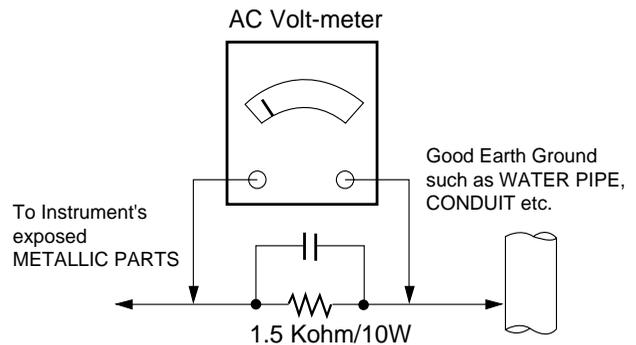
Please use only a plastic screwdriver to protect yourself from shock hazard during service operation.

\triangle WARNING

BE CAREFUL ELECTRIC SHOCK !

- If you want to replace with the new backlight (CCFL) or inverter circuit, must disconnect the AC adapter because high voltage appears at inverter circuit about 650Vrms.
- Handle with care wires or connectors of the inverter circuit. If the wires are pressed cause short and may burn or take fire.

Leakage Current Hot Check Circuit



SERVICING PRECAUTIONS

CAUTION: Before servicing receivers covered by this service manual and its supplements and addenda, read and follow the **SAFETY PRECAUTIONS** on page 3 of this publication.

NOTE: If unforeseen circumstances create conflict between the following servicing precautions and any of the safety precautions on page 3 of this publication, always follow the safety precautions. Remember: Safety First.

General Servicing Precautions

1. Always unplug the receiver AC power cord from the AC power source before;
 - a. Removing or reinstalling any component, circuit board module or any other receiver assembly.
 - b. Disconnecting or reconnecting any receiver electrical plug or other electrical connection.
 - c. Connecting a test substitute in parallel with an electrolytic capacitor in the receiver.
CAUTION: A wrong part substitution or incorrect polarity installation of electrolytic capacitors may result in an explosion hazard.
 - d. Discharging the picture tube anode.
2. Test high voltage only by measuring it with an appropriate high voltage meter or other voltage measuring device (DVM, FETVOM, etc) equipped with a suitable high voltage probe.
Do not test high voltage by "drawing an arc".
3. Discharge the picture tube anode only by (a) first connecting one end of an insulated clip lead to the degaussing or kine aquadag grounding system shield at the point where the picture tube socket ground lead is connected, and then (b) touch the other end of the insulated clip lead to the picture tube anode button, using an insulating handle to avoid personal contact with high voltage.
4. Do not spray chemicals on or near this receiver or any of its assemblies.
5. Unless specified otherwise in this service manual, clean electrical contacts only by applying the following mixture to the contacts with a pipe cleaner, cotton-tipped stick or comparable non-abrasive applicator; 10% (by volume) Acetone and 90% (by volume) isopropyl alcohol (90%-99% strength)
CAUTION: This is a flammable mixture.
Unless specified otherwise in this service manual, lubrication of contacts is not required.
6. Do not defeat any plug/socket B+ voltage interlocks with which receivers covered by this service manual might be equipped.
7. Do not apply AC power to this instrument and/or any of its electrical assemblies unless all solid-state device heat sinks are correctly installed.
8. Always connect the test receiver ground lead to the receiver chassis ground before connecting the test receiver positive lead.
Always remove the test receiver ground lead last.

9. Use with this receiver only the test fixtures specified in this service manual.

CAUTION: Do not connect the test fixture ground strap to any heat sink in this receiver.

Electrostatically Sensitive (ES) Devices

Some semiconductor (solid-state) devices can be damaged easily by static electricity. Such components commonly are called *Electrostatically Sensitive (ES) Devices*. Examples of typical ES devices are integrated circuits and some field-effect transistors and semiconductor "chip" components. The following techniques should be used to help reduce the incidence of component damage caused by static by static electricity.

1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, drain off any electrostatic charge on your body by touching a known earth ground. Alternatively, obtain and wear a commercially available discharging wrist strap device, which should be removed to prevent potential shock reasons prior to applying power to the unit under test.
2. After removing an electrical assembly equipped with ES devices, place the assembly on a conductive surface such as aluminum foil, to prevent electrostatic charge buildup or exposure of the assembly.
3. Use only a grounded-tip soldering iron to solder or unsolder ES devices.
4. Use only an anti-static type solder removal device. Some solder removal devices not classified as "anti-static" can generate electrical charges sufficient to damage ES devices.
5. Do not use freon-propelled chemicals. These can generate electrical charges sufficient to damage ES devices.
6. Do not remove a replacement ES device from its protective package until immediately before you are ready to install it. (Most replacement ES devices are packaged with leads electrically shorted together by conductive foam, aluminum foil or comparable conductive material).
7. Immediately before removing the protective material from the leads of a replacement ES device, touch the protective material to the chassis or circuit assembly into which the device will be installed.
CAUTION: Be sure no power is applied to the chassis or circuit, and observe all other safety precautions.
8. Minimize bodily motions when handling unpackaged replacement ES devices. (Otherwise harmless motion such as the brushing together of your clothes fabric or the lifting of your foot from a carpeted floor can generate static electricity sufficient to damage an ES device.)

General Soldering Guidelines

1. Use a grounded-tip, low-wattage soldering iron and appropriate tip size and shape that will maintain tip temperature within the range of 500° F to 600° F.
2. Use an appropriate gauge of RMA resin-core solder composed of 60 parts tin/40 parts lead.
3. Keep the soldering iron tip clean and well tinned.
4. Thoroughly clean the surfaces to be soldered. Use a small wire-bristle (0.5 inch, or 1.25cm) brush with a metal handle.

Do not use freon-propelled spray-on cleaners.

5. Use the following unsoldering technique
 - a. Allow the soldering iron tip to reach normal temperature.
(500° F to 600° F)
 - b. Heat the component lead until the solder melts.
 - c. Quickly draw the melted solder with an anti-static, suction-type solder removal device or with solder braid.
6. Use the following soldering technique.
 - a. Allow the soldering iron tip to reach a normal temperature (500° F to 600° F)
 - b. First, hold the soldering iron tip and solder the strand against the component lead until the solder melts.

- c. Quickly move the soldering iron tip to the junction of the component lead and the printed circuit foil, and hold it there only until the solder flows onto and around both the component lead and the foil.

CAUTION: Work quickly to avoid overheating the circuit board printed foil.

- d. Closely inspect the solder area and remove any excess or splashed solder with a small wire-bristle brush.

IC Remove/Replacement

Some chassis circuit boards have slotted holes (oblong) through which the IC leads are inserted and then bent flat against the circuit foil. When holes are the slotted type, the following technique should be used to remove and replace the IC. When working with boards using the familiar round hole, use the standard technique as outlined in paragraphs 5 and 6 above.

Removal

1. Desolder and straighten each IC lead in one operation by gently prying up on the lead with the soldering iron tip as the solder melts.
2. Draw away the melted solder with an anti-static suction-type solder removal device (or with solder braid) before removing the IC.

Replacement

1. Carefully insert the replacement IC in the circuit board.
2. Carefully bend each IC lead against the circuit foil pad and solder it.
3. Clean the soldered areas with a small wire-bristle brush. (It is not necessary to reapply acrylic coating to the areas).

"Small-Signal" Discrete Transistor

Removal/Replacement

1. Remove the defective transistor by clipping its leads as close as possible to the component body.
2. Bend into a "U" shape the end of each of three leads remaining on the circuit board.
3. Bend into a "U" shape the replacement transistor leads.
4. Connect the replacement transistor leads to the corresponding leads extending from the circuit board and crimp the "U" with long nose pliers to insure metal to metal contact then solder each connection.

Power Output, Transistor Device

Removal/Replacement

1. Heat and remove all solder from around the transistor leads.
2. Remove the heat sink mounting screw (if so equipped).
3. Carefully remove the transistor from the heat sink of the circuit board.
4. Insert new transistor in the circuit board.
5. Solder each transistor lead, and clip off excess lead.
6. Replace heat sink.

Diode Removal/Replacement

1. Remove defective diode by clipping its leads as close as possible to diode body.
2. Bend the two remaining leads perpendicular y to the circuit board.
3. Observing diode polarity, wrap each lead of the new diode around the corresponding lead on the circuit board.
4. Securely crimp each connection and solder it.
5. Inspect (on the circuit board copper side) the solder joints of the two "original" leads. If they are not shiny, reheat them and if necessary, apply additional solder.

Fuse and Conventional Resistor

Removal/Replacement

1. Clip each fuse or resistor lead at top of the circuit board hollow stake.
2. Securely crimp the leads of replacement component around notch at stake top.
3. Solder the connections.

CAUTION: Maintain original spacing between the replaced component and adjacent components and the circuit board to prevent excessive component temperatures.

Circuit Board Foil Repair

Excessive heat applied to the copper foil of any printed circuit board will weaken the adhesive that bonds the foil to the circuit board causing the foil to separate from or "lift-off" the board. The following guidelines and procedures should be followed whenever this condition is encountered.

At IC Connections

To repair a defective copper pattern at IC connections use the following procedure to install a jumper wire on the copper pattern side of the circuit board. (Use this technique only on IC connections).

1. Carefully remove the damaged copper pattern with a sharp knife. (Remove only as much copper as absolutely necessary).
2. Carefully scratch away the solder resist and acrylic coating (if used) from the end of the remaining copper pattern.
3. Bend a small "U" in one end of a small gauge jumper wire and carefully crimp it around the IC pin. Solder the IC connection.
4. Route the jumper wire along the path of the out-away copper pattern and let it overlap the previously scraped end of the good copper pattern. Solder the overlapped area and clip off any excess jumper wire.

At Other Connections

Use the following technique to repair the defective copper pattern at connections other than IC Pins. This technique involves the installation of a jumper wire on the component side of the circuit board.

1. Remove the defective copper pattern with a sharp knife.

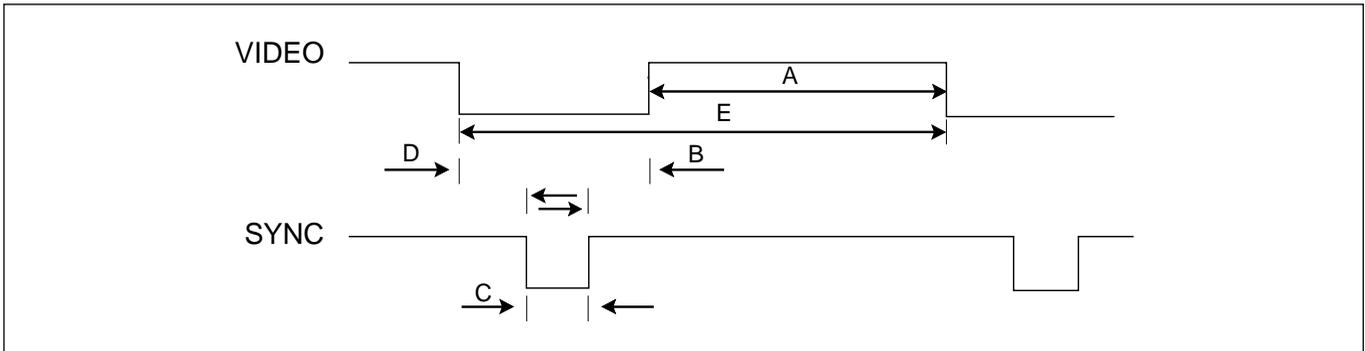
Remove at least 1/4 inch of copper, to ensure that a hazardous condition will not exist if the jumper wire opens.

2. Trace along the copper pattern from both sides of the pattern break and locate the nearest component that is directly connected to the affected copper pattern.
3. Connect insulated 20-gauge jumper wire from the lead of the nearest component on one side of the pattern break to the lead of the nearest component on the other side.

Carefully crimp and solder the connections.

CAUTION: Be sure the insulated jumper wire is dressed so the it does not touch components or sharp edges.

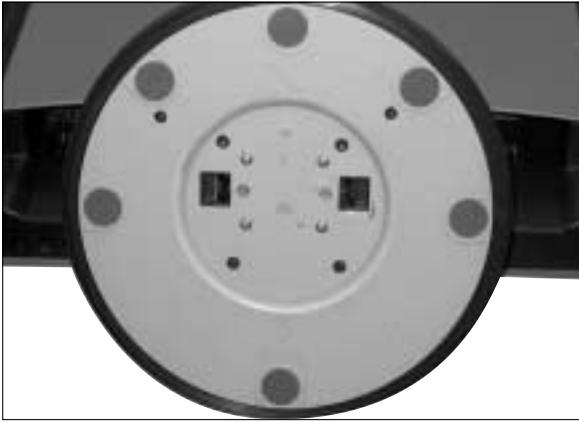
TIMING CHART



MODE	H / V	Sync Polarity	Dot Clock	Frequency	Total Period (E)	Video Active Time (A)	Sync Duration (D)	Front Porch (C)	Blanking Time (B)	Resolution
1	H(Pixels)	+	25.175	31.469	800	640	16	96	48	640 x 350
	V(Lines)	-		70.09	449	350	37	2	60	
2	H(Pixels)	-	28.321	31.468	900	720	18	108	54	720 X 400
	V(Lines)	+		70.08	449	400	12	2	35	
3	H(Pixels)	-	25.175	31.469	800	640	16	96	48	640 x 480
	V(Lines)	-		59.94	525	480	10	2	33	
4	H(Pixels)	-	31.5	37.5	840	640	16	64	120	640 x 480
	V(Lines)	-		75	500	480	1	3	16	
5	H(Pixels)	+	40.0	37.879	1056	800	40	128	88	800 x 600
	V(Lines)	+		60.317	628	600	1	4	23	
6	H(Pixels)	+	49.5	46.875	1056	800	16	80	160	800 x 600
	V(Lines)	+		75.0	625	600	1	3	21	
7	H(Pixels)	+/-	57.283	49.725	1152	832	32	64	224	832 x 624
	V(Lines)	+/-		74.55	667	624	1	3	39	
8	H(Pixels)	-	65.0	48.363	1344	1024	24	136	160	1024 x 768
	V(Lines)	-		60.0	806	768	3	6	29	
9	H(Pixels)	-	78.75	60.123	1312	1024	16	96	176	1024 x 768
	V(Lines)	-		75.029	800	768	1	3	28	
10	H(Pixels)	+/-	100.0	68.681	1456	1152	32	128	144	1152 x 870
	V(Lines)	+/-		75.062	915	870	3	3	39	
11	H(Pixels)	+/-	92.978	61.805	1504	1152	18	134	200	1152 x 900
	V(Lines)	+/-		65.96	937	900	2	4	31	
12	H(Pixels)	+	108.0	63.981	1688	1280	48	112	248	1280 x 1024
	V(Lines)	+		60.02	1066	1024	1	3	38	
13	H(Pixels)	+	135.0	79.976	1688	1280	16	144	248	1280 x 1024
	V(Lines)	+		75.035	1066	1024	1	3	38	

DISASSEMBLY

1



1. Put a soft cushion on the floor and lay the stand on its side so that the base is accessible.

4



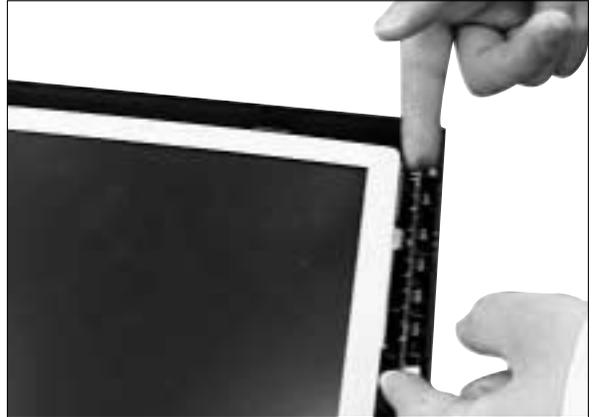
4. Cover the panel with your hand so that it is not scratched. Then, pull up the cabinet corner side.

2



2. Hold the set while folding the latch and take out the stand base.

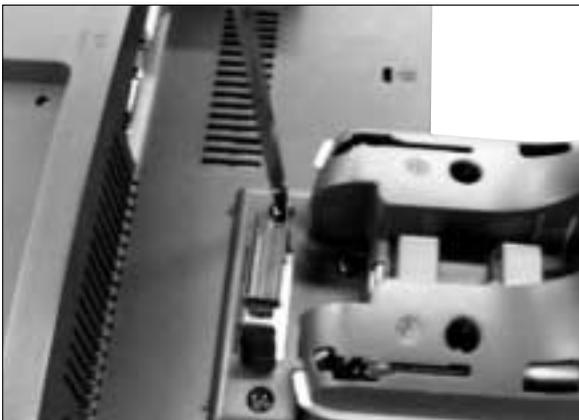
5



5-1. Disassemble the cabinet.

5-2. Hold the control PCB as shown in the figure and gently pull it out.

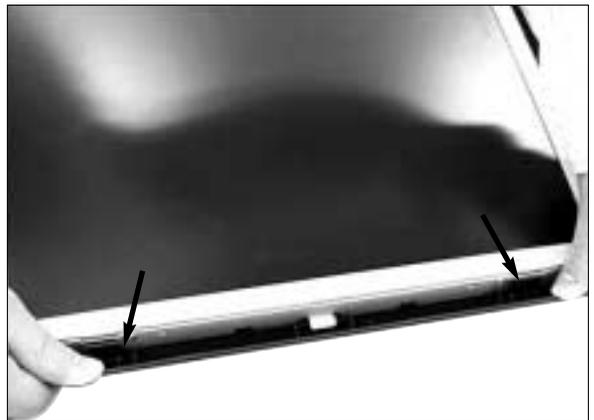
3



3-1. Push the cover upward and remove it.

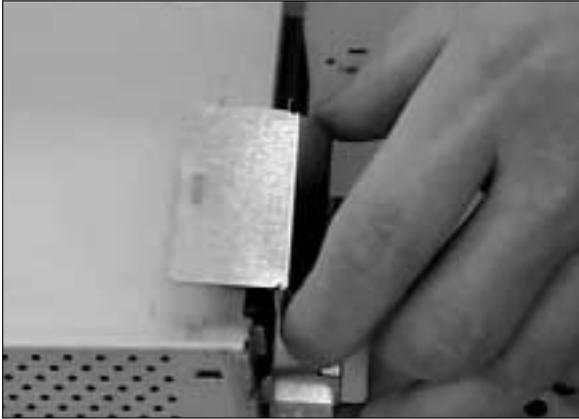
3-2. Unscrew the four screws.

6



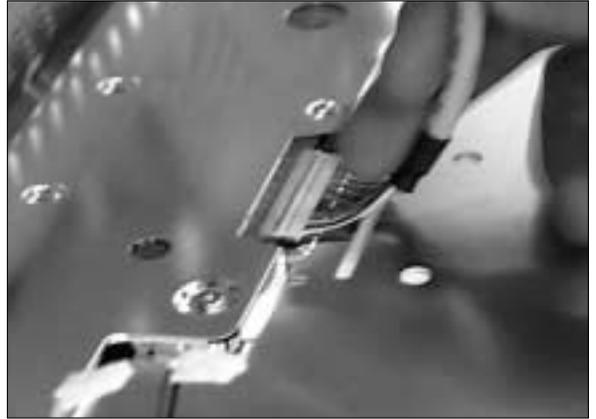
6. Push up the back cover as shown in the figure and pull out the chassis assembly so that the latch is untied.

7



7. Push the shield cap upward and disassemble it.

9



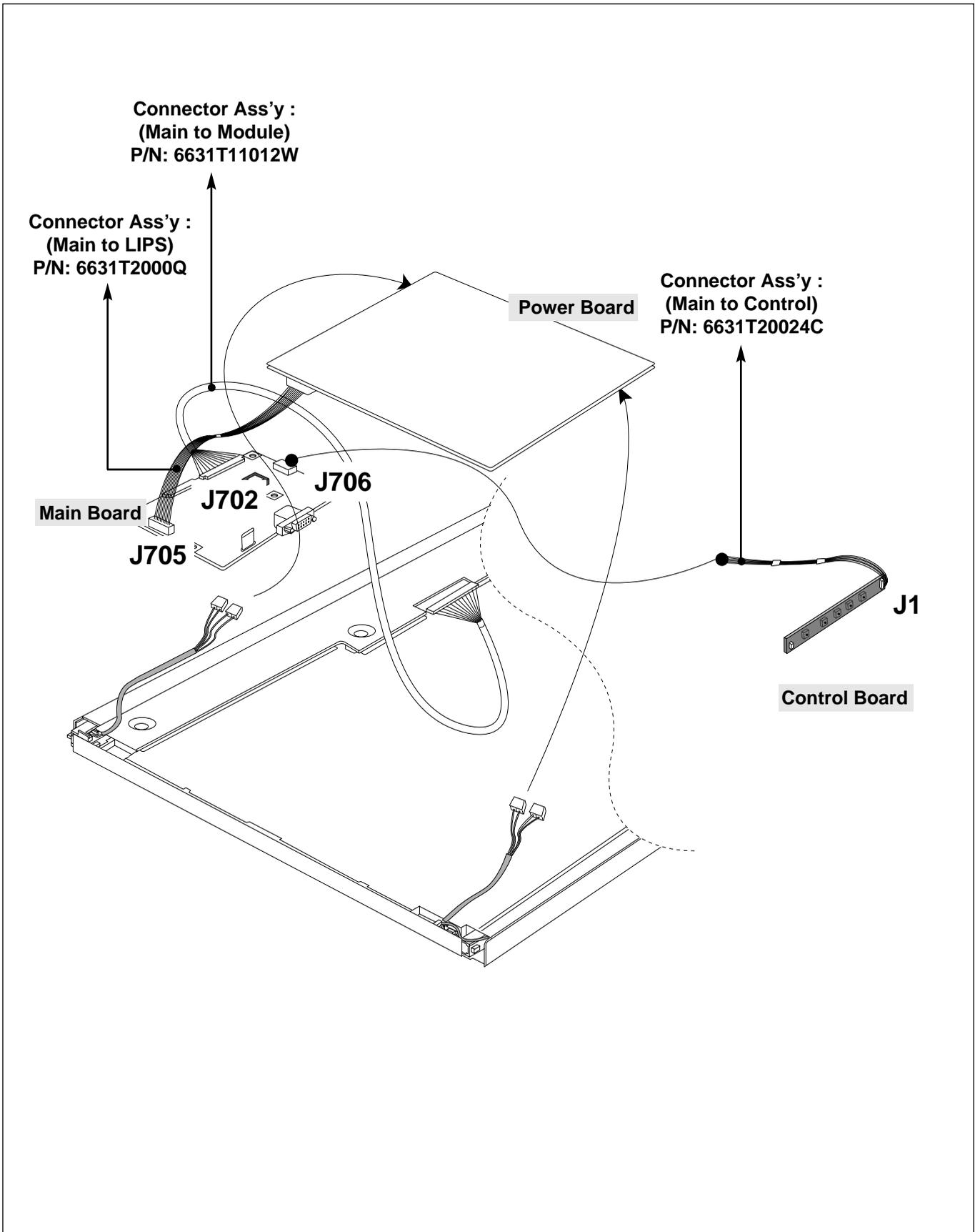
9. Pull out the link cable while pushing up the main frame.

8

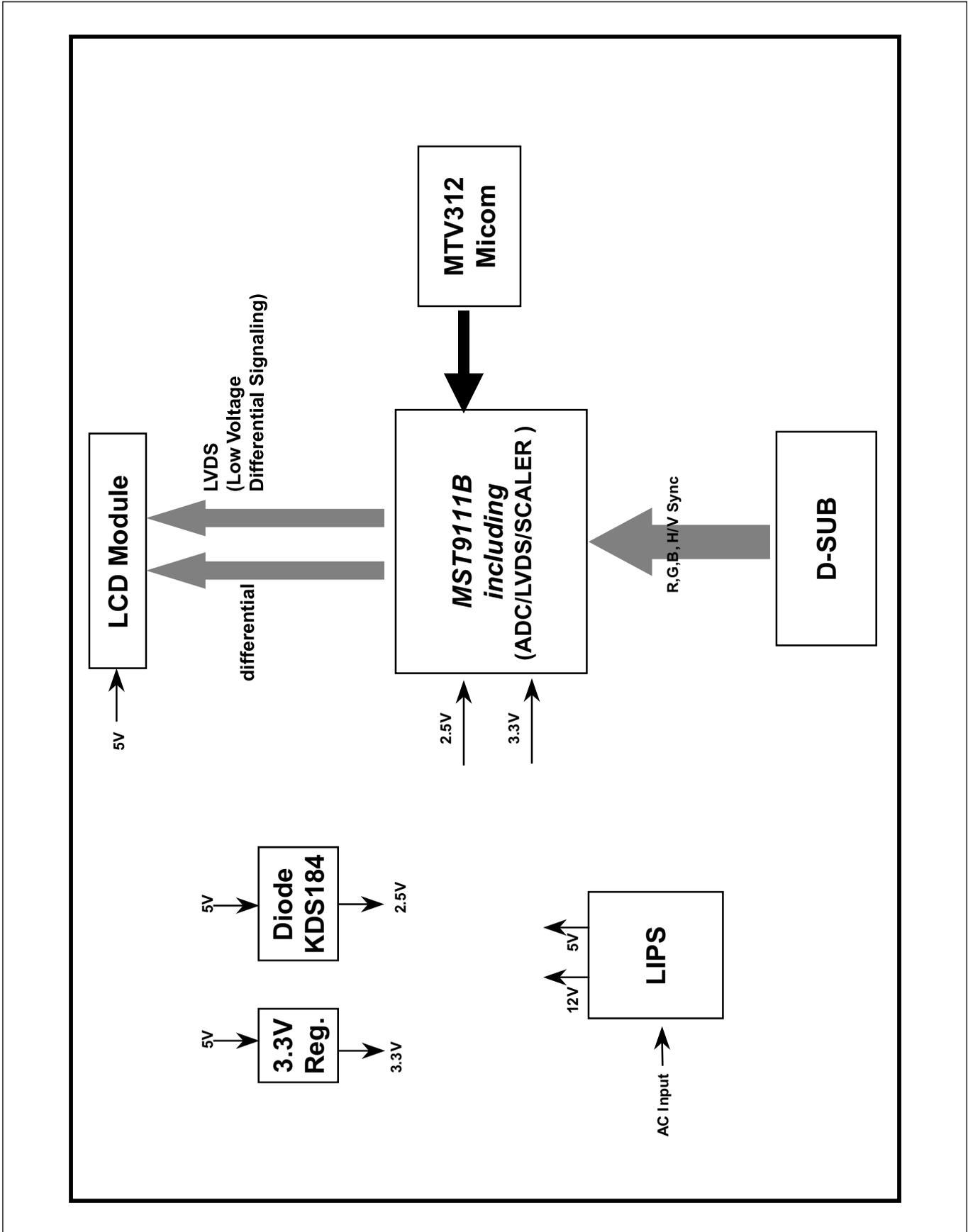


8. Pull out the cable.

WIRING DIAGRAM



BLOCK DIAGRAM



DESCRIPTION OF BLOCK DIAGRAM

1. Video Controller Part.

This part amplifies the level of video signal for the digital conversion and converts from the analog video signal to the digital video signal using a pixel clock.

The pixel clock for each mode is generated by the PLL.

The range of the pixel clock is from 25MHz to 135MHz.

This part consists of the Scaler, ADC, LVDS transmitter.

The Scaler gets the video signal converted analog to digital, interpolates input to 1280 X 1024 resolution signal and outputs 8-bit R, G, B signal to transmitter.

2. Power Part.

This part consists of the one 3.3V, and one 1.8V regulators to convert power which is provided 5V in Power board. 12V is provided for inverter, 5V is provided for LCD panel and 5V for micom.

Also, 5V is converted 3.3V and 1.8V by regulator. Converted power is provided for IC in the main board.

The inverter converts from DC12V to AC 600Vrms and operates back-light lamps of module.

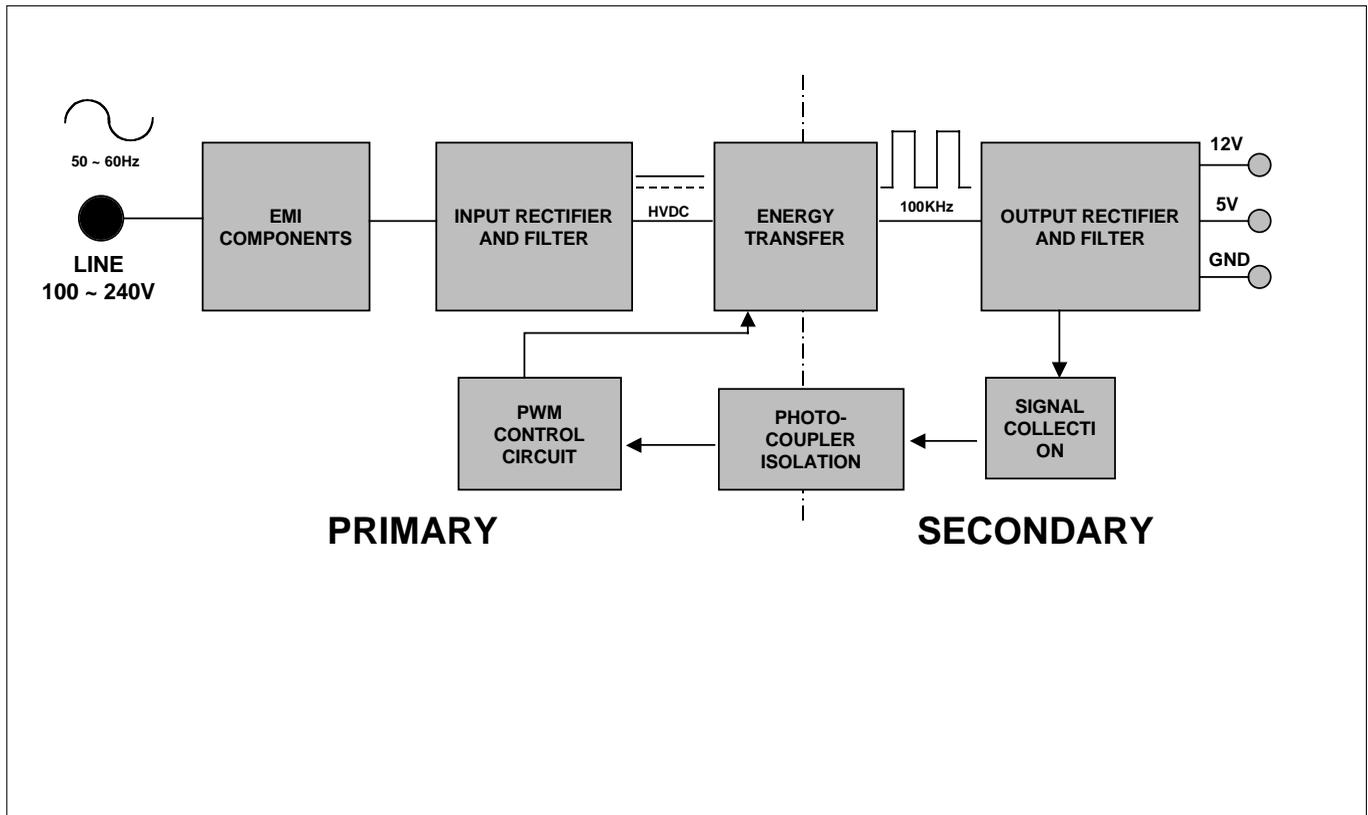
3. MICOM Part.

This part consists of EEPROM IC which stores control data, Reset IC and the Micom.

The Micom distinguishes polarity and frequency of the H/V sync are supplied from signal cable.

The controlled data of each modes is stored in EEPROM.

LIPS Board Block Diagram



Operation description_LIPS

1. EMI components.

This part contains of EMI components to comply with global marketing EMI standards like FCC,VCCI CISPR, the circuit included a line-filter, across line capacitor and of course the primary protection fuse.

2. Input rectifier and filter.

This part function is for transfer the input AC voltage to a DC voltage through a bridge rectifier and a bulk capacitor.

3. Energy Transfer.

This part function is for transfer the primary energy to secondary through a power transformer.

4. Output rectifier and filter.

This part function is to make a pulse width modulation control and to provide the driver signal to power switch,to adjust the duty cycle during different AC input and output loading condition to achieve the dc output stabilized, and also the over power protection is also monitor by this part.

5. Photo-Coupler isolation.

This part function is to feed back the dc output changing status through a photo transistor to primary controller to achieve the stabilized dc output voltage.

6. Signal collection.

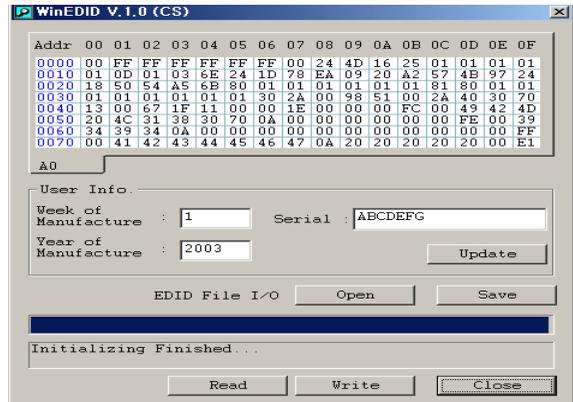
This part function is to collect the any change from the dc output and feed back to the primary through photo transistor

ADJUSTMENT

Windows EDID V1.0 User Manual

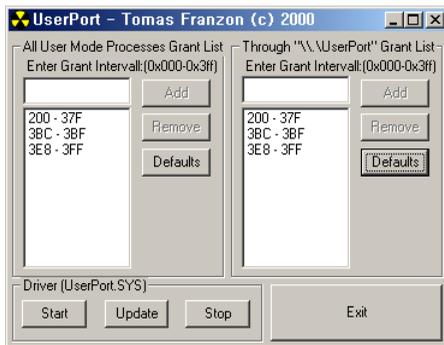
Operating System: MS Windows 98, 2000, XP
 Port Setup: Windows 98 => Don't need setup
 Windows 2000, XP => Need to Port Setup.
 This program is available to LCD Monitor only.

2. EDID Read & Write
 - 1) Run WinEDID.exe



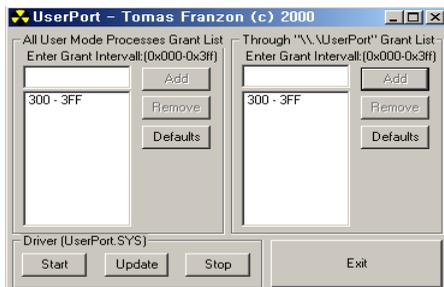
1. Port Setup

- a) Copy "UserPort.sys" file to "c:\WINNT\system32\drivers" folder
- b) Run Userport.exe

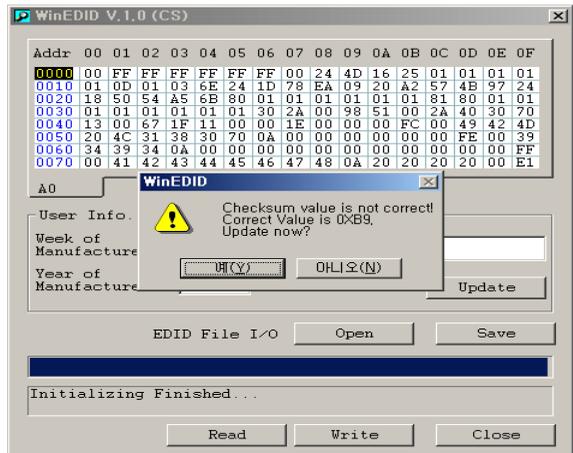


- 2) Edit Week of Manufacture, Year of Manufacture, Serial Number
 - a) Input User Info Data
 - b) Click "Update" button
 - c) Click " Write" button

- c) Remove all default number
- d) Add 300-3FF



- e) Click Start button.
- f) Click Exit button.



SERVICE OSD

- 1) Turn off the power switch at the front side of display.
- 2) Press MENU, POWER Switch.
- 3) Shows the service OSD menu.
- 4) The service OSD menu contains additional menus that the User OSD menu as described below.
 - a) CLEAR ETI : To initialize using time.
 - b) AUTO COLOR : W/B balance and Automatically sets the gain and offset value.
 - c) AGING : Select Aging mode(on/off).
 - d) PANEL : Select using panel.
 - e) NVRAM INIT : EEPROM initialize(24C08).
 - f) 9300 : Allows you to set the R/G/B.-9300K value manually.
 - g) 6500 : Allows you to set the R/G/B.-6500K value manually.
 - h) OFFSET : Allows you to set the R/G/B.-Offset value manually.(Analog Only)
 - i) GAIN : Allows you to set the R/G/B.-Gain value manually.(Analog Only)

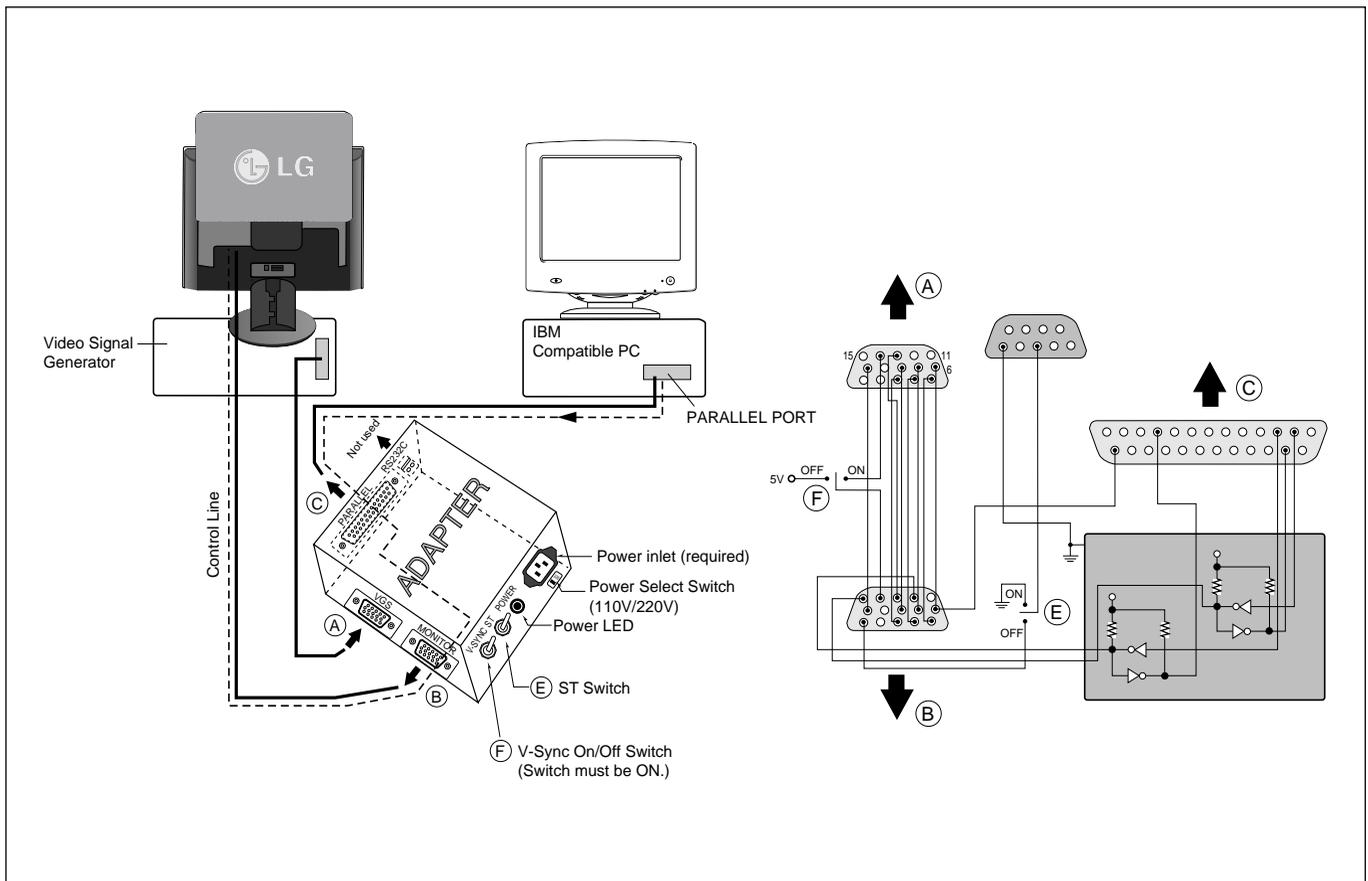
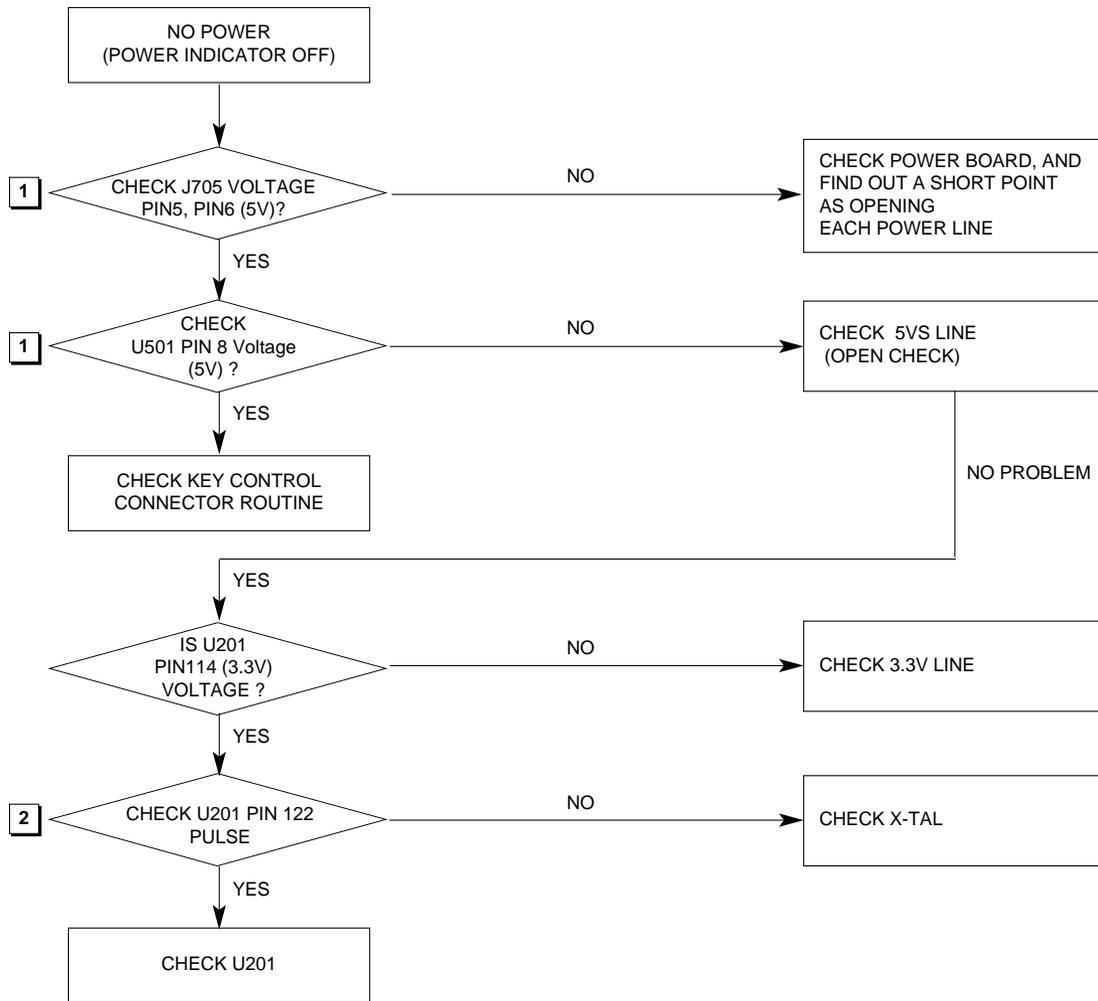


Figure 1. Cable Connection

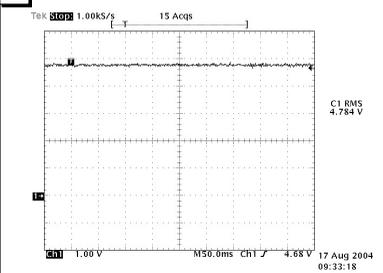
TROUBLESHOOTING GUIDE

1. NO POWER

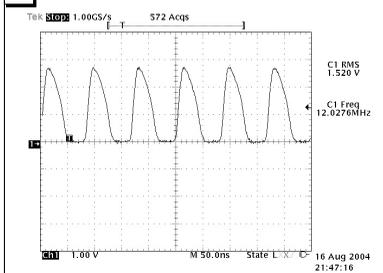


Waveforms

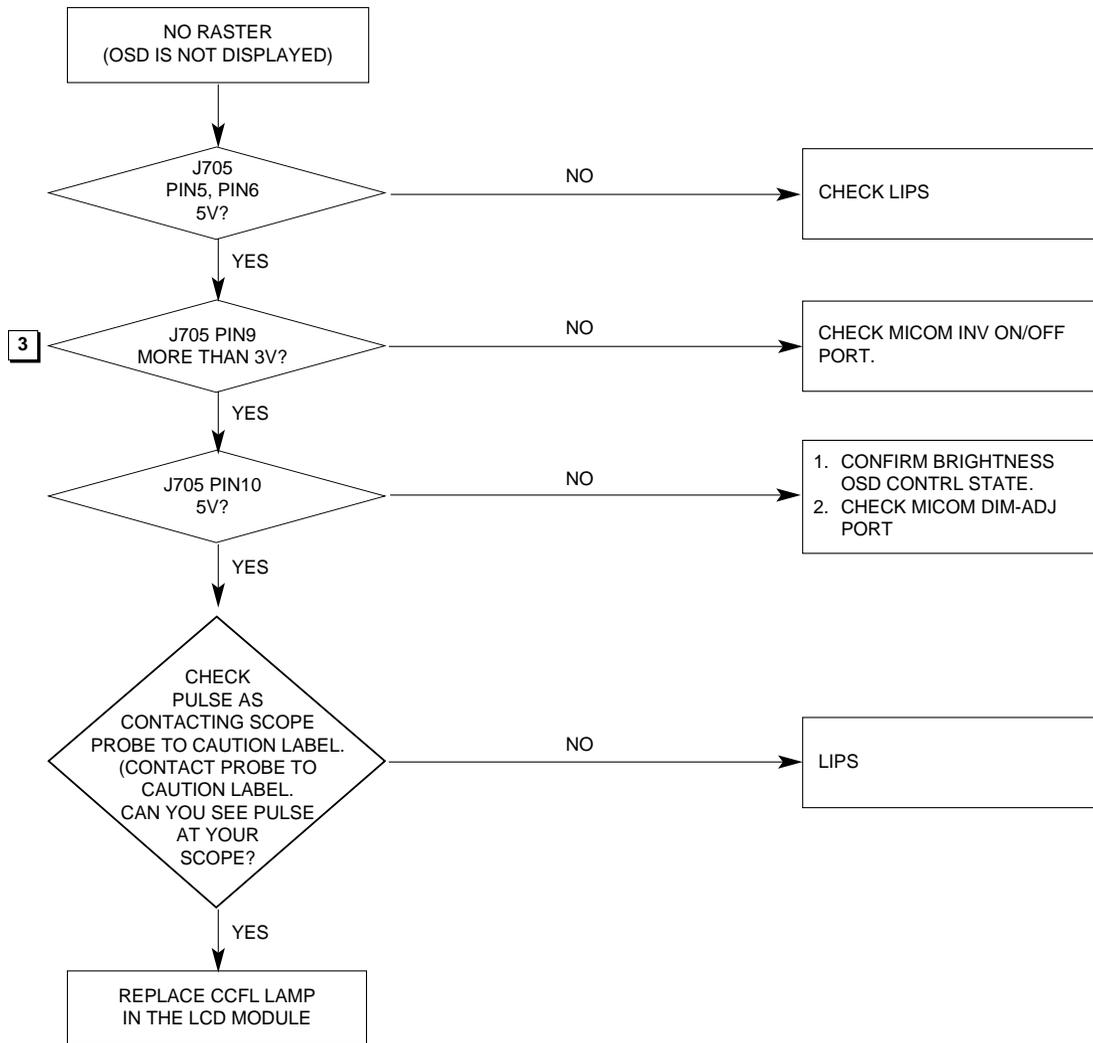
1 J705-#5, 6 / U501-#8



2 U201-#122

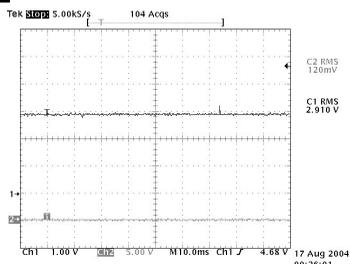


2. NO RASTER (OSD IS NOT DISPLAYED) – LIPS

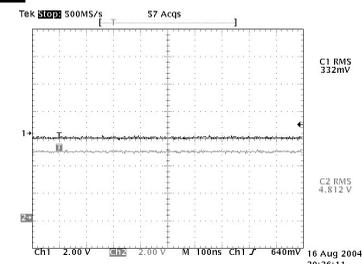


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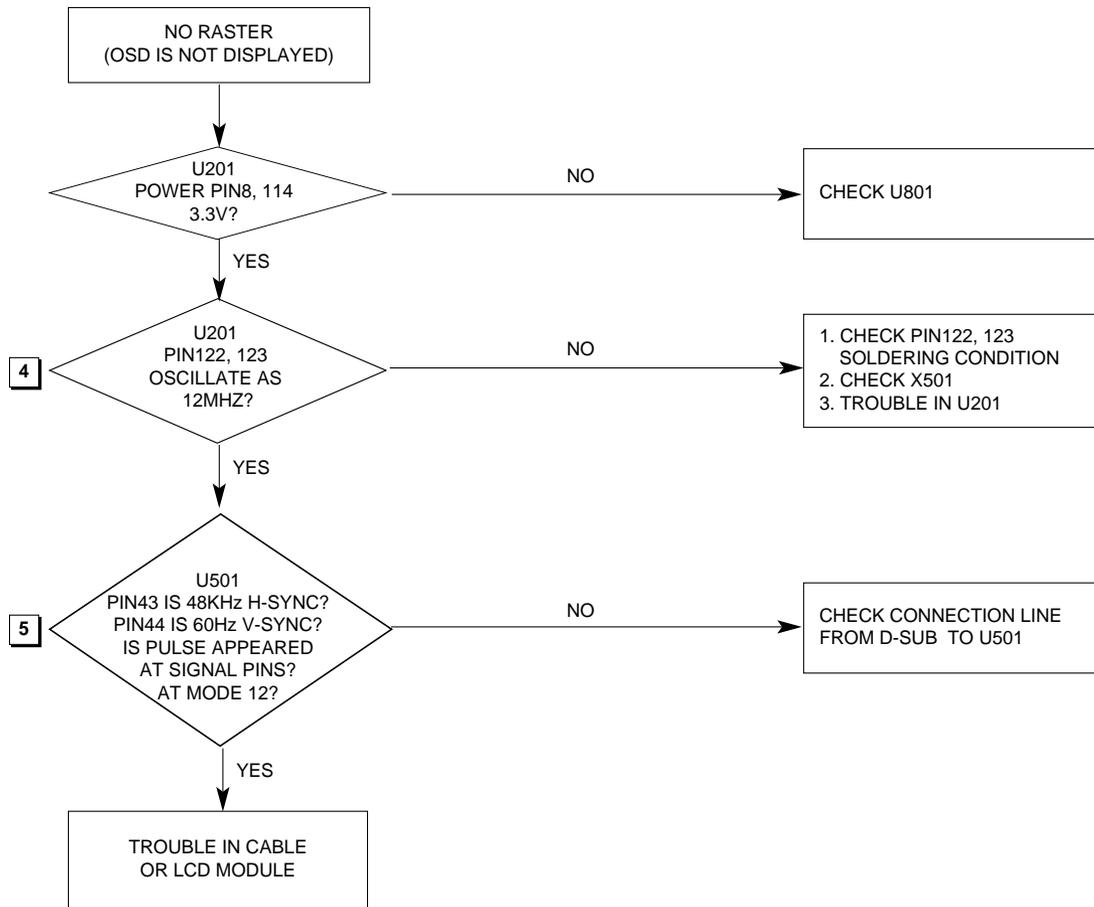
3 J705-#9



3 J705-#9

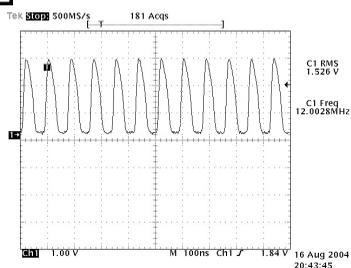


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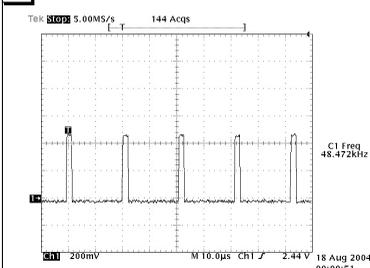


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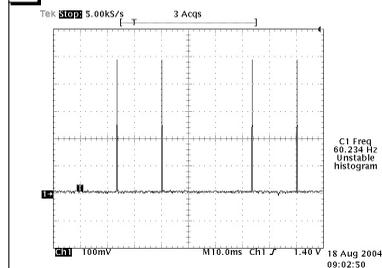
4 U201-#122, 123



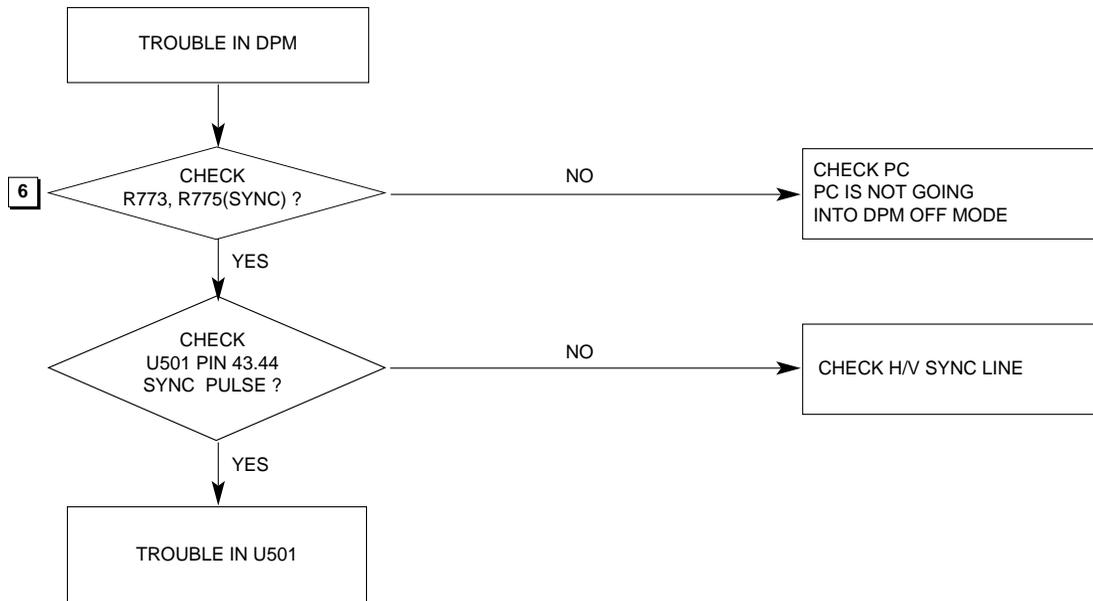
5 U501-#43 H-SYNC



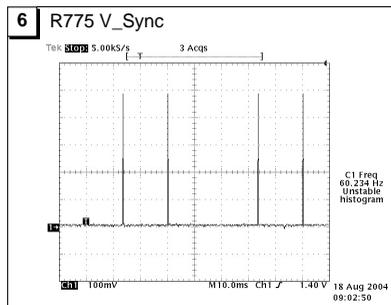
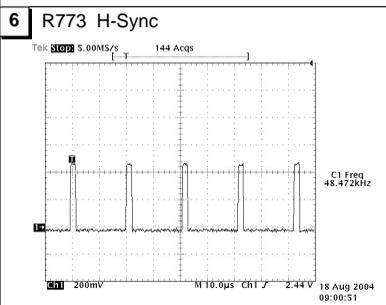
5 U501-#44 V-SYNC



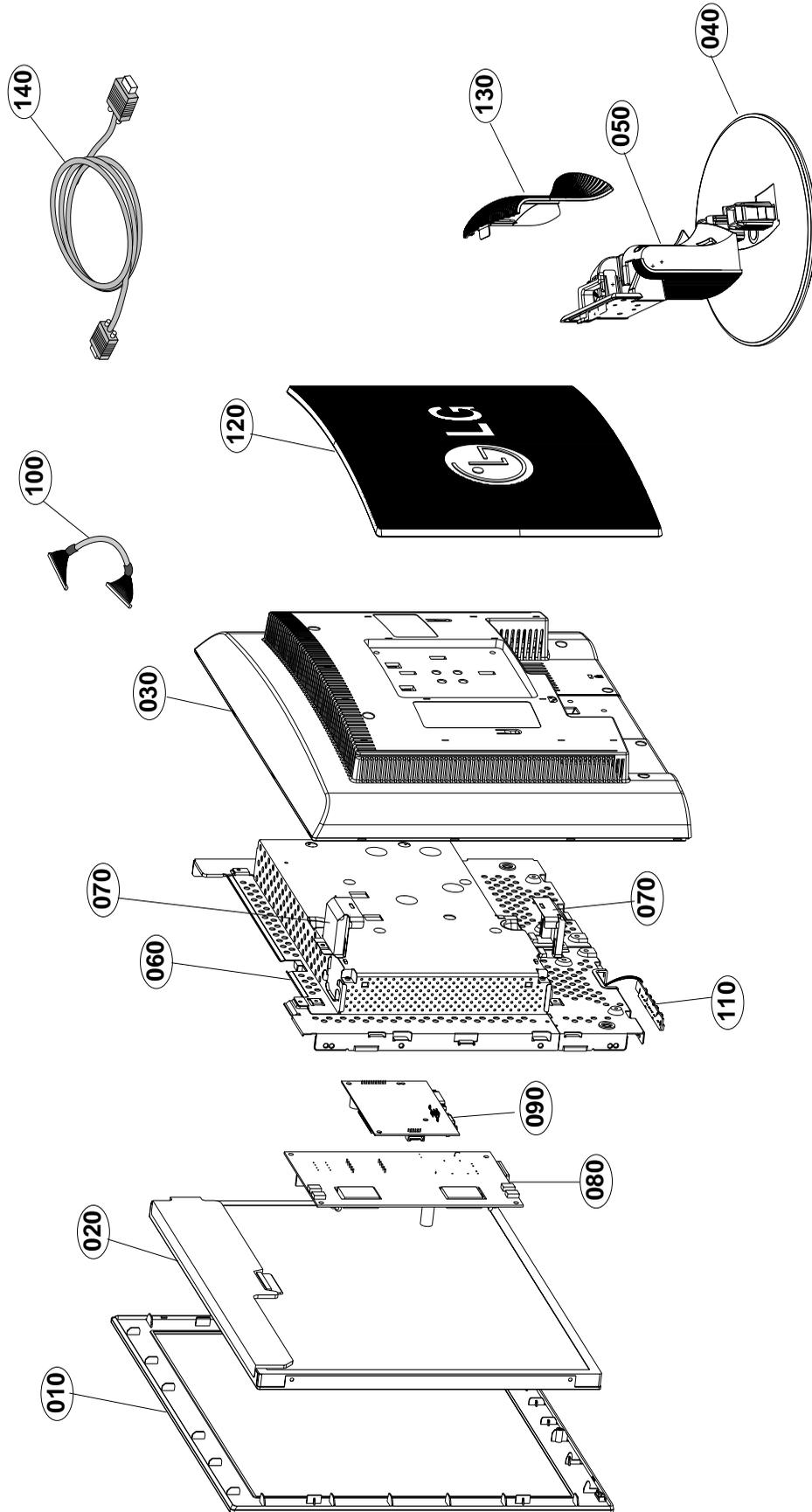
4. TROUBLE IN DPM



Waveforms



EXPLODED VIEW



EXPLODED VIEW PARTS LIST

Ref. No.	Part No.	Description
010	3091TKL125G	CABINET ASSEMBLY L1930SQ BRAND L094 SLIVER A-CKD
020	6304FLP142A	LCD(LIQUID CRYSTAL DISPLAY), LM190E03-B4K1 LG PHILPS TFT COLOR 20T,TN,250NITS,SXGA,LVDS
030	3809TKL078C	BACK COVER ASSEMBLY, L1930S .. ""A""-CKD"
040	3043TKK147N	TILT SWIVEL ASSEMBLY, L1730 , ""E""-WA LOCAL"
	3043TKK147K	TILT SWIVEL ASSEMBLY, 1930S NT LOCAL -FOR CHINA
050	3043TKK204E	TILT SWIVEL ASSEMBLY, L1930 , SLIVER ""145M""-WA LOCAL"
	3043TKK145X	TILT SWIVEL ASSEMBLY, 1930S SILVER -NT LOCAL
060	4951TKS145S	METAL ASSEMBLY, FRAME TN("""Q""-CKD)"
070	4814TKK268B	SHIELD,INVERTER ""A""-CKD"
080	6871TPT271Y	PWB(PCB) ASSEMBLY, POWER, M-CHASSIS 1719 POWER TOTAL LIEN CHANG SOCKET,2PIN,CY101/2 1000PF 450V
	6871TPT271P	PWB(PCB) ASSEMBLY,POWER, M-CHASSIS 1719 POWER TOTAL LIEN CHANG SOCKET,2PIN,CY101/2 1000PF
090	3313TL9063A	MAIN TOTAL ASSEMBLY, L1930SQM BRAND CL-64
100	6631T11012W	CONNECTOR ASSEMBLY, 30P H-H 200MM UL20276 LG708G
110	6871TST541A	PWB(PCB) ASSEMBLY,SUB, L1730BM CONTROL TOTAL BRAND CONTROL
120	3550TKK512D	COVER, L1930S BACK DOOR ""B""-CKD"
130	3550TKK452D	COVER, LXX30 STAND REAR COVER_ ""B""-CKD"
140	6850TD9007C	CABLE,D-SUB, UL20276-9C(5.8MM) DT L1800MM, CORE POS400MM BLACK(9930) L1730 DM

REPLACEMENT PARTS LIST

CAUTION: BEFORE REPLACING ANY OF THESE COMPONENTS,
READ CAREFULLY THE **SAFETY PRECAUTIONS** IN THIS MANUAL.

* NOTE : **S** SAFETY Mark **AL** ALTERNATIVE PARTS

DATE: 2004. 08. 23.				
*S	*AL	LOC. NO.	PART NO.	DESCRIPTION / SPECIFICATION
MAIN BOARD				
CAPACITORS				
		C204	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C205	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C206	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C207	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C208	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C209	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C210	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C211	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C214	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C215	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C216	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C217	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C218	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C219	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C220	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C221	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C222	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C223	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C225	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C226	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C227	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C230	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C231	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C232	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C233	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C240	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C251	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C501	OCC101CK41A	100PF 1608 50V 5% R/TP NP0
		C502	OCC101CK41A	100PF 1608 50V 5% R/TP NP0
		C503	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C504	OCH8106F611	10UF 16V M 85STD(CYL) R/TP
		C506	OCC030CK01A	3PF 1608 50V 0.25 PF R/TP NP0
		C507	OCC180CK41A	18PF 1608 50V 5% R/TP NP0
		C508	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C701	OCK105CD56A	1UF 1608 10V 10% R/TP X7R
		C703	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C708	OCK103CK51A	0.01UF 1608 50V 10% R/TP B(Y5)
		C709	OCK103CK51A	0.01UF 1608 50V 10% R/TP B(Y5)
		C710	OCK103CK51A	0.01UF 1608 50V 10% R/TP B(Y5)
		C711	OCK103CK51A	0.01UF 1608 50V 10% R/TP B(Y5)
		C717	OCC101CK41A	100PF 1608 50V 5% R/TP NP0
		C718	OCC101CK41A	100PF 1608 50V 5% R/TP NP0
		C719	OCC680CK41A	68PF 1608 50V 5% R/TP NP0
		C720	OCC101CK41A	100PF 1608 50V 5% R/TP NP0
		C721	OCC680CK41A	68PF 1608 50V 5% R/TP NP0
		C727	OCK105CD56A	1UF 1608 10V 10% R/TP X7R
		C732	OCK103CK51A	0.01UF 1608 50V 10% R/TP B(Y5)
		C733	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C734	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C735	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C760	OCE107EF610	"100UF KMG,RD 16V 20% FL BULK"
		C801	OCK103CK51A	0.01UF 1608 50V 10% R/TP B(Y5)

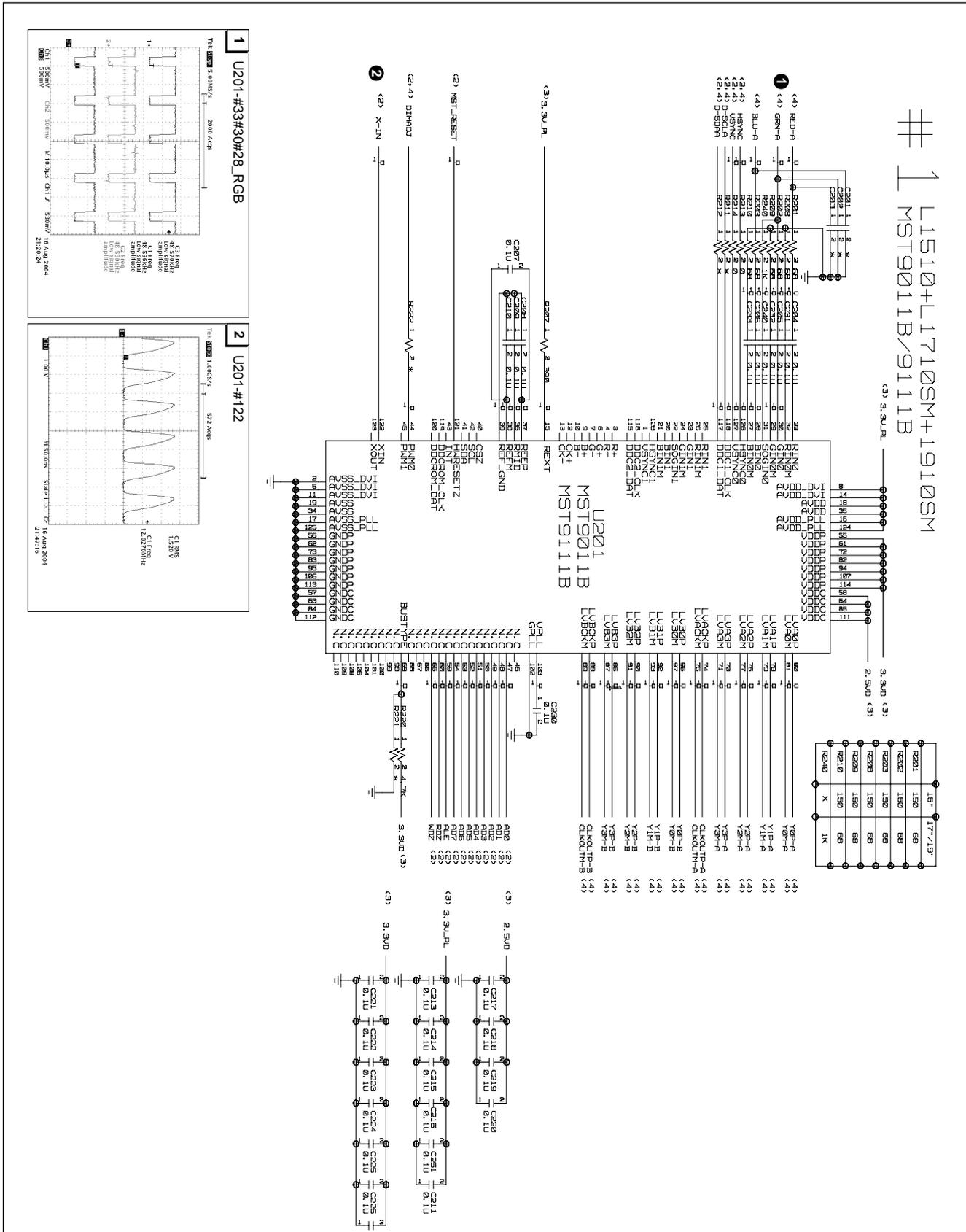
DATE: 2004. 08. 23.				
*S	*AL	LOC. NO.	PART NO.	DESCRIPTION / SPECIFICATION
		C803	OCE107EF610	"100UF KMG,RD 16V 20% FL BULK"
		C804	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C805	OCK105CD56A	1UF 1608 10V 10% R/TP X7R
		C806	OCK103CK51A	0.01UF 1608 50V 10% R/TP B(Y5)
		C807	OCE107EF610	"100UF KMG,RD 16V 20% FL BULK"
		C808	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C809	OCK103CK51A	0.01UF 1608 50V 10% R/TP B(Y5)
		C810	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C812	OCE107EF610	"100UF KMG,RD 16V 20% FL BULK"
		C814	OCE107EF610	"100UF KMG,RD 16V 20% FL BULK"
		C815	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C816	OCK103CK51A	0.01UF 1608 50V 10% R/TP B(Y5)
		C817	OCK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C818	OCC102CK41A	1000PF 1608 50V 5% R/TP NP0
DIODEs				
		D701	0DS226009AA	KDS226 TP KEC SOT-23 80V 300
		D702	0DS226009AA	KDS226 TP KEC SOT-23 80V 300
		D706	0DS226009AA	KDS226 TP KEC SOT-23 80V 300
		D804	0DD184009AA	KDS184 TP KEC - 85V - - - 300
		D805	0DD184009AA	KDS184 TP KEC - 85V - - - 300
		ZD701	0DZ560009GB	BZT52C5V6S DIODES R/TP SOD323
		ZD702	0DZ560009GB	BZT52C5V6S DIODES R/TP SOD323
		ZD703	0DZ560009GB	BZT52C5V6S DIODES R/TP SOD323
		ZD704	0DZ560009GB	BZT52C5V6S DIODES R/TP SOD323
		ZD705	0DZ560009GB	BZT52C5V6S DIODES R/TP SOD323
		ZD711	0DZ560009GB	BZT52C5V6S DIODES R/TP SOD323
ICs				
		U201	0IPRPM3008B	"MST9111B(ANALOG) MSTAR 128P,L"
		U501	0IZZTSZ550A	MYSON MTV312 L1930SQM -E
		U502	0ISG240860B	M24C08W6 SGS-THOMSON 8SOP R/T
		U801	0IPMGKE011A	KIA78D33F KEC DPAK R/TP 3.3V
		U802	0TFVI80023A	VISHAY SI3865DV R/TP TSOP-6 8
TRANSISTOR				
		Q502	0IKE704200H	KIA7042AP TO-92 TP 4.2 VOLT.
		Q503	0TR390409AE	FAIRCHILD KST3904(LGEMTF) TP
		Q504	0TR390409AE	FAIRCHILD KST3904(LGEMTF) TP
		Q505	0TR390409AE	FAIRCHILD KST3904(LGEMTF) TP
		Q703	0TR390609FA	KST3906-MTF TP SAMSUNG SOT23
		Q704	0TR390609FA	KST3906-MTF TP SAMSUNG SOT23
		Q706	0TR390409AE	FAIRCHILD KST3904(LGEMTF) TP
		Q707	0TR390409AE	FAIRCHILD KST3904(LGEMTF) TP
RESISTORs				
		R201	0RJ0682D677	68 OHM 1/10 W 5% 1608 R/TP
		R202	0RJ0682D677	68 OHM 1/10 W 5% 1608 R/TP
		R203	0RJ0682D677	68 OHM 1/10 W 5% 1608 R/TP
		R207	0RJ3900D677	390 OHM 1/10 W 5% 1608 R/TP

DATE: 2004. 08. 23.				
*S	*AL	LOC. NO.	PART NO.	DESCRIPTION / SPECIFICATION
		R208	0RJ0682D677	68 OHM 1/10 W 5% 1608 R/TP
		R209	0RJ0682D677	68 OHM 1/10 W 5% 1608 R/TP
		R210	0RJ0682D677	68 OHM 1/10 W 5% 1608 R/TP
		R213	0RJ0000D677	0 OHM 1/10 W 5% 1608 R/TP
		R214	0RJ0000D677	0 OHM 1/10 W 5% 1608 R/TP
		R220	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R240	0RJ1001D677	1K OHM 1/10 W 5% 1608 R/TP
		R506	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R508	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R512	0RJ0332D677	33 OHM 1/10 W 5% 1608 R/TP
		R513	0RJ0332D677	33 OHM 1/10 W 5% 1608 R/TP
		R514	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R515	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R516	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R518	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R519	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R520	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R521	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R522	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R523	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R524	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R525	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R526	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R527	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R528	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R529	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R531	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R532	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R534	0RJ0000D677	0 OHM 1/10 W 5% 1608 R/TP
		R535	0RJ3301D677	3.3K OHM 1/10 W 5% 1608 R/TP
		R537	0RJ3301D677	3.3K OHM 1/10 W 5% 1608 R/TP
		R541	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R542	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R543	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R544	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R545	0RJ4700D677	470 OHM 1/10 W 5% 1608 R/TP
		R546	0RJ0000D677	0 OHM 1/10 W 5% 1608 R/TP
		R547	0RJ4700D677	470 OHM 1/10 W 5% 1608 R/TP
		R548	0RJ0332D677	33 OHM 1/10 W 5% 1608 R/TP
		R549	0RJ0332D677	33 OHM 1/10 W 5% 1608 R/TP
		R555	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R556	0RJ4700D677	470 OHM 1/10 W 5% 1608 R/TP
		R557	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R560	0RJ4702D677	47000 OHM 1/10 W 5% 1608 R/TP
		R561	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R563	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R564	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R565	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R566	0RJ1002D677	10K OHM 1/10 W 5% 1608 R/TP
		R701	0RJ0752D677	75 OHM 1/10 W 5% 1608 R/TP
		R703	0RJ0752D677	75 OHM 1/10 W 5% 1608 R/TP
		R706	0RJ0752D677	75 OHM 1/10 W 5% 1608 R/TP
		R708	0RJ4700D677	470 OHM 1/10 W 5% 1608 R/TP
		R709	0RJ1001D677	1K OHM 1/10 W 5% 1608 R/TP
		R716	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R717	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R720	0RJ0000D677	0 OHM 1/10 W 5% 1608 R/TP
		R722	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R723	0RJ0332D677	33 OHM 1/10 W 5% 1608 R/TP
		R724	0RJ0332D677	33 OHM 1/10 W 5% 1608 R/TP
		R726	0RJ1002D677	10K OHM 1/10 W 5% 1608 R/TP
		R727	0RJ1002D677	10K OHM 1/10 W 5% 1608 R/TP

DATE: 2004. 08. 23.				
*S	*AL	LOC. NO.	PART NO.	DESCRIPTION / SPECIFICATION
		R737	0RJ0000D677	0 OHM 1/10 W 5% 1608 R/TP
		R744	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R745	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R747	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R748	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R769	0RJ0000D677	0 OHM 1/10 W 5% 1608 R/TP
		R772	0RJ1001D677	1K OHM 1/10 W 5% 1608 R/TP
		R773	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R774	0RJ1001D677	1K OHM 1/10 W 5% 1608 R/TP
		R775	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R779	0RJ0682D677	68 OHM 1/10 W 5% 1608 R/TP
		R780	0RJ2001D677	2K OHM 1/10 W 5% 1608 R/TP
		R781	0RJ2001D677	2K OHM 1/10 W 5% 1608 R/TP
		R782	0RJ0102D677	10 OHM 1/10 W 5% 1608 R/TP
		R783	0RJ0102D677	10 OHM 1/10 W 5% 1608 R/TP
		R803	0RJ0000D677	0 OHM 1/10 W 5% 1608 R/TP
		R807	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R808	0RJ0000D677	0 OHM 1/10 W 5% 1608 R/TP
		R810	0RJ0000D677	0 OHM 1/10 W 5% 1608 R/TP
		R814	0RJ2202D677	22K OHM 1/10 W 5% 1608 R/TP
		R815	0RJ5600D677	560 OHM 1/10 W 5% 1608 R/TP
		R821	0RJ0000D677	0 OHM 1/10 W 5% 1608 R/TP
		R822	0RJ0000D677	0 OHM 1/10 W 5% 1608 R/TP
		R824	0RJ0000D677	0 OHM 1/10 W 5% 1608 R/TP
OTHERS				
		X501	6212AA2004A	HC-49U TXC 12.0MHZ +/- 30 PPM
CONTROL BOARD				
		C1	0CK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		C2	0CK104CK56A	0.1UF 1608 50V 10% R/TP X7R
		LED1	0DLLT0340AA	LITEON LTL-14CDJNHP1 BK GREE
		Q1	0TR390409AE	FAIRCHILD KST3904(LGEMTF) TP
		Q2	0TR390409AE	FAIRCHILD KST3904(LGEMTF) TP
		R1	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R2	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R3	0RJ2001D677	2K OHM 1/10 W 5% 1608 R/TP
		R4	0RJ2001D677	2K OHM 1/10 W 5% 1608 R/TP
		R5	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R7	0RJ4700D677	470 OHM 1/10 W 5% 1608 R/TP
		R8	0RJ4700D677	470 OHM 1/10 W 5% 1608 R/TP
		SW2	140-058E	SKHV10910B LGEC NON 12V 20A H
		SW3	140-058E	SKHV10910B LGEC NON 12V 20A H
		SW6	140-058E	SKHV10910B LGEC NON 12V 20A H
		SW7	140-058E	SKHV10910B LGEC NON 12V 20A H
		SW8	140-058E	SKHV10910B LGEC NON 12V 20A H

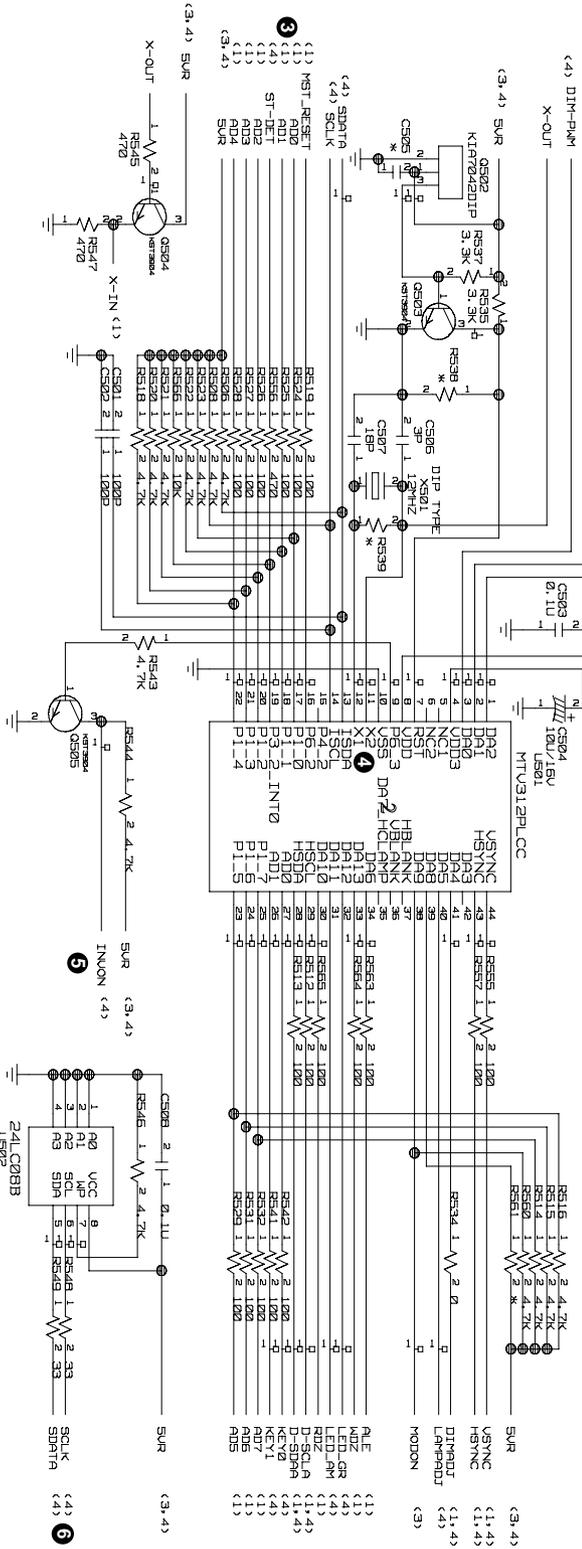
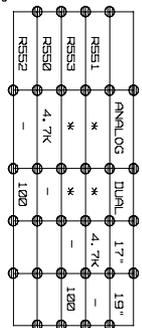
SCHEMATIC DIAGRAM

1. SCALER

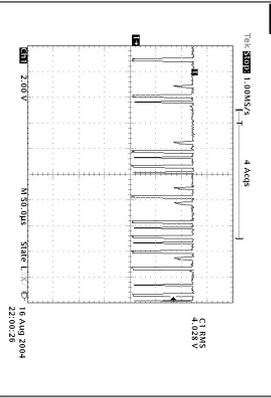


2. MICOM

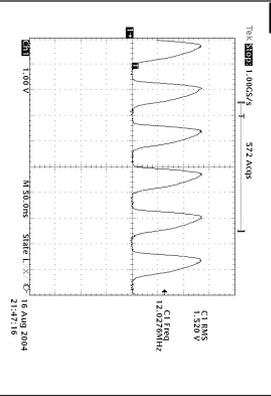
#2 LIS10+L1710SM+1910SM



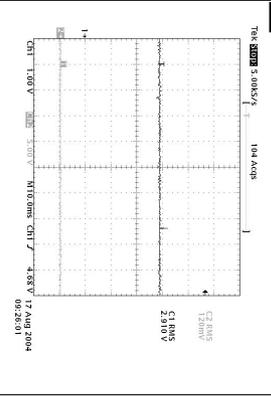
3 U501-#17-#22



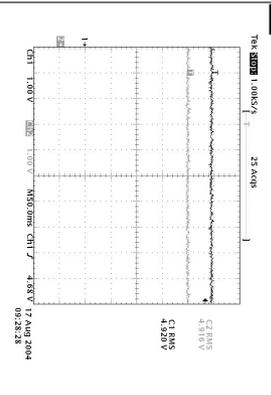
4 U501-#11, #12



5 O505-#3



6 U502-#6, #6





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